

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT6245208

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHI-LIN LIU	07/23/2020
SHANG-CHIH HSIEH	07/23/2020
JIAN-SING LI	08/11/2020
WEI-HSIANG MA	07/23/2020
YI-HSUN CHEN	07/29/2020
CHEOK-KEI LEI	07/23/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
<b>Street Address:</b>	8, LI-HSIN RD. 6
<b>Internal Address:</b>	HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16883524
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(612)332-9081
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	(612) 332-5300
<b>Email:</b>	kwacek@merchantgould.com
<b>Correspondent Name:</b>	MARK L. GLEASON
<b>Address Line 1:</b>	MERCHANT & GOULD P.C.
<b>Address Line 2:</b>	P.O. BOX 2903
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402-0903
<b>ATTORNEY DOCKET NUMBER:</b>	17829.0104USU1/P20190347U
<b>NAME OF SUBMITTER:</b>	MARK L. GLEASON
<b>SIGNATURE:</b>	/Mark L. Gleason/
<b>DATE SIGNED:</b>	08/11/2020

PATENT

**Total Attachments: 12**

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NP- 25343- 0- 03- B3

76(S)

Atty. Docket No.: 17829.0104USU1/P20190347US01

PATENT ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at 8, Li-Hsin Rd. 6 Hsinchu Science Park, Hsinchu 300-78 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications, and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	MULTIPLEXER	
SIGNATURE OF INVENTOR AND NAME	Chi-Lin Liu	<i>Chi-Lin Liu</i>
DATE	2020/7/23	
RESIDENCE	1F., No.105, Siwei St., Yonghe Dist., New Taipei City 23453, Taiwan	

PATENT ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at 8, Li-Hsin Rd. 6 Hsinchu Science Park, Hsinchu 300-78 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

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Atty. Docket No.: 17829.0104USU1/P20190347US01

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	MULTIPLEXER	
SIGNATURE OF INVENTOR AND NAME	Shang-Chih Hsieh	<i>Shang-Chih Hsieh</i>
DATE	7/23/20	
RESIDENCE	No.5, Aly. 5, Ln. 429, Xinnong St., Yangmei City, Taoyuan County 326, Taiwan	

**PATENT ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	MULTIPLEXER	
SIGNATURE OF INVENTOR AND NAME	Jian-Sing LI	<i>Jian-Sing Li</i>
DATE	2020.8.11	
RESIDENCE	1F., No.105, Siwei St., Yonghe Dist., New Taipei City 23453, Taiwan	



Atty. Docket No.: 17829.0104USU1/P20190347US01

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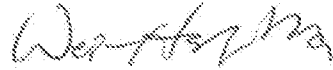
NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	MULTIPLEXER	
SIGNATURE OF INVENTOR AND NAME	Wei-Hsiang Ma	
DATE	2024/07/23	
RESIDENCE	Taipei City, Taiwan	

PATENT ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year:

TITLE OF INVENTION	MULTIPLEXER	
SIGNATURE OF INVENTOR AND NAME	Yi-Hsun Chen	<i>Yi-Hsun Chen</i>
DATE	<i>2020/9/29</i>	
RESIDENCE	Taiwan	

PATENT ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	MULTIPLEXER	
SIGNATURE OF INVENTOR AND NAME	Cheok-Kei Lei	LEI CHEOK KEI
DATE	2020/7/23	
RESIDENCE	416 Rua Cidade Santarem Edif.Wak Dor Lei 10 Andar AC Macau	